Winstar Display Co., LTD





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SPECIFICATION

CUSTOMER :		
MODULE NO.:	WG12864B-	CFK-T#N
APPROVED BY:		
(FOR CUSTOMER USE ONLY)	PCB VERSION:	DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2011.01.17		First issue



MODLE NO :

DEC		MOLONI		DOC. FIRST ISSUE
REC	ORDS OF REV	ISION		
VERSION	DATE	REVISED PAGE NO.		SUMMARY
0	2011.01.17		Fin	rst issue

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1. Module Classification Information

$$\underline{W}\underline{G}$$
 $\underline{12864}$
 $\underline{B}-\underline{C}\underline{F}\underline{K}-\underline{T\#N}$
 $\underline{\$}$
 $\underline{\$}$

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type

③ Display Font: 128*64 Dots

4 Model serials no.

⑤ Backlight Type: N→Without backlight C→Triple Color B/L

> B→EL, Blue green A→LED, Amber D→EL, Green $R \rightarrow LED$, Red W→EL, White O→LED, Orange F→CCFL, White G→LED, Green

Y→LED, Yellow Green $T\rightarrow$ LED, White

 LCD Mode: B→TN Positive, Gray T→FSTN Negative

N→TN Negative,

G→STN Positive, Gray

Y→STN Positive, Yellow Green

M→STN Negative, Blue

F→FSTN Positive

② LCD Polarizer A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00

direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00

> E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code T: Build in Negative Voltage and temperature compensation

N: IC NT7107C,NT7108C

#:Fit in with the ROHS Directions and regulations

2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8). Winstar have the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9). Winstar have the right to change the PCB Rev.

3.General Specification

Item	Dimension	Unit					
Number of Characters	128 x 64 Dots	_					
Module dimension	75.0 x 52.7 x 8.9(MAX)	mm					
View area	60.0 x 32.6	mm					
Active area	55.01 x 27.49	mm					
Dot size	0.4 x 0.4	mm					
Dot pitch	0.43 x 0.43	mm					
LCD type	FSTN Positive Transflective (In LCD production, It will occur slightly color of can only guarantee the same color in the same based on the same based of the same based of the same based on th						
Duty	1/64						
View direction	12 o'clock						
Backlight Type	Triple color B/L(RED ,Green ,Blue)						

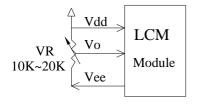
4. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T_{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	V _I	0	_	$V_{ m DD}$	V
Supply Voltage For Logic	$V_{ m DD}$	0	_	6.7	V
Supply Voltage For LCD	V _{DD} -V _{LCD}	0	_	16.7	V

5.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	4.5	5.0	5.5	V
		Ta=-20°C	_	_	9.6	V
Supply Voltage For LCD	V_{DD} - V_0	Ta=25°C	_	8.0	_	V
*Note		Ta=+70°C	7.6	_	_	V
Input High Volt.	V_{IH}	_	2.0	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	0	_	0.8	V
Output High Volt.	V_{OH}	_	2.4	_	V_{DD}	V
Output Low Volt.	V _{OL}	_	0	_	0.4	V
Supply Current	I_{DD}	_	3.0	4.0	5.0	mA

^{*} Note: Please design the VOP adjustment circuit on customer's main board

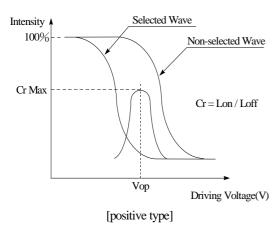


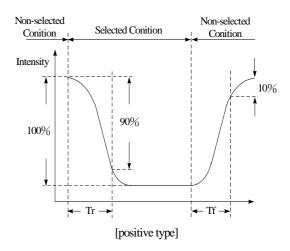
6.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V) θ	CR≧2	30	_	60	deg
View Angle	(H) φ	CR≧2	-45	_	45	deg
Contrast Ratio	CR	_	_	5	_	_
D	T rise	_	_	150	200	ms
Response Time	T fall	_	_	150	200	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)



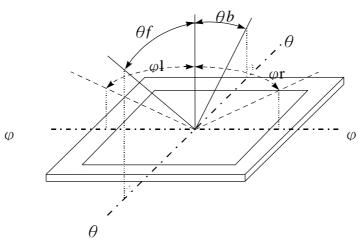


Conditions:

Operating Voltage : Vop Viewing Angle(θ , φ) : 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle ($CR \ge 2$)

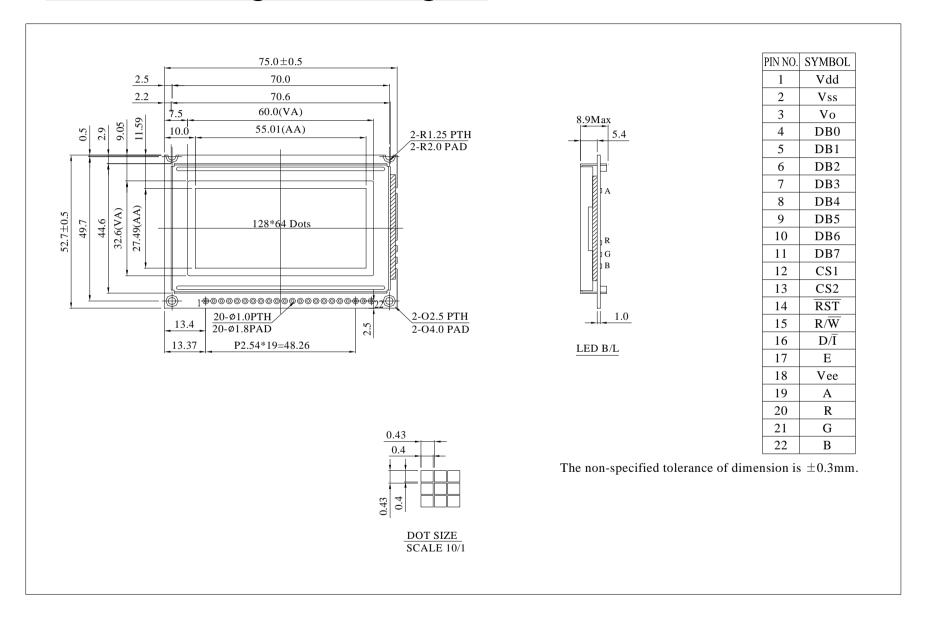


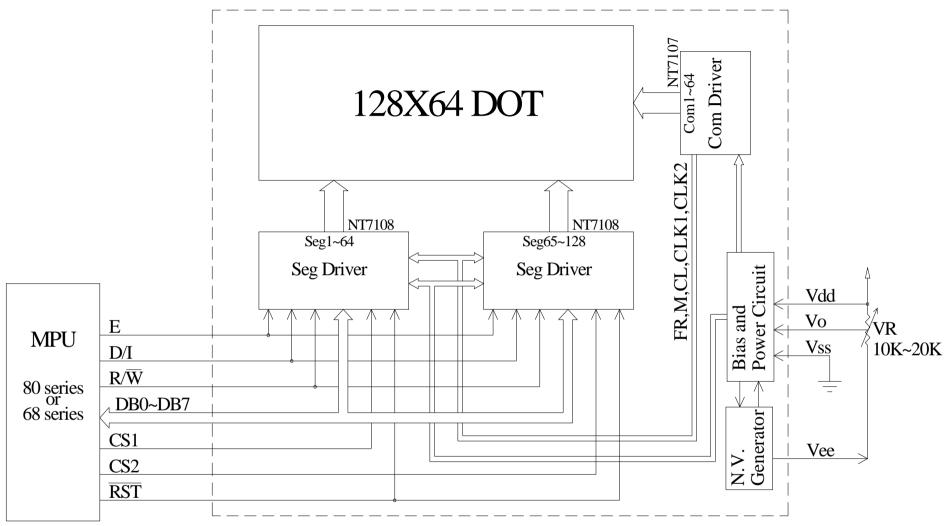
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7.Interface Description

Pin No.	Symbol	Level	Description					
1	Vdd	5.0V	Power supply (+5V)					
2	V_{SS}	0V	Power supply (GND)					
3	V_{o}	(Variable)	Contrast Adjustment					
4	DB0	H/L	Data bus line					
5	DB1	H/L	Data bus line					
6	DB2	H/L	Data bus line					
7	DB3	H/L	Data bus line					
8	DB4	H/L	Data bus line					
9	DB5	H/L	Data bus line					
10	DB6	H/L	Data bus line					
11	DB7	H/L	Data bus line					
12	CS1	L	Select Column 1~ Column 64					
13	CS2	L	Select Column 65~ Column 128					
14	RST	L	Reset signal					
15	R/W	H/L	H: Read (MPU←Module), L: Write (MPU→Module)					
16	D/I	H/L	H: Data, L: Instruction					
17	E	Н	Enable signal					
18	Vee	_	Negative Voltage output					
19	A	_	Power Supply for LED (+)					
20	R	_	Power Supply for LED Red					
21	G		Power Supply for LED Green					
22	В		Power Supply for LED Blue					

8. Contour Drawing & Block Diagram





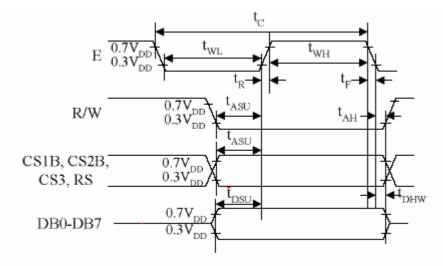
External contrast adjustment.

9.Timing Characteristics

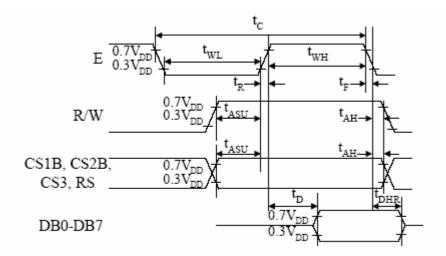
MPU Interface

 $(T=25^{\circ}C, VDD=+5.0V\pm0.5)$

Characteristic	Symbol	Min	Тур	Max	Unit
E cycle	tcyc	1000	_	_	ns
E high level width	twhE	450	_	_	ns
E low level width	twlE	450	_	_	ns
E rise time	tr	_	_	25	ns
E tall time	tf	_	_	25	ns
Address set-up time	tas	140	_	_	ns
Address hold time	tah	10	_	_	ns
Data set-up time	tdsw	140	_	_	ns
Data delay time	tddr	_	_	320	ns
Data hold time (write)	tdhw	10	_	_	ns
Data hold time (read)	tdhr	20	_	_	ns



MPU Write Timing



MPU Read Timing

10.Display Control Instruction

The display control instructions control the internal state of the NT7108. Instruction is received from MPU to NT7108 for the display control. The following table shows various instructions.

Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function
Display on/off	L	L	L	L	Н	Н	Н	Н	Н	L/H	Controls the display on or off. Internal status and display RAM data is not affected. L:OFF, H:ON
Set address (Y address)	L	L	L	Н			addres	-	-		Sets the Y address in the Y address counter.
Set page (X address)	L	L	Н	L	Н	Н	MPU	IPU Read Timing			Sets the X address at the X address register.
Display Start line (Z address)	L	L	Н	Н		Display start line (0-63)				Indicates the display data RAM displayed at the top of the screen.	
Status read	L	Н	Busy	L	On/ Off	Reset	L	L	L	L	Read status. BUSY L: Ready H: In operation ON/OFF L: Display ON H: Display OFF RESET L: Normal H: Reset
Write display data	Н	L				Write data				Writes data (DB0: 7) into display data RAM. After writing instruction, Y address is increased by 1 automatically.	
Read display data	Н	Н				Read data				Reads data (DB0: 7) from display data RAM to the data bus.	

11.Detailed Explanation

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	1	1	D

The display data appears when D is 1 and disappears when D is 0. Though the data is not on the

screen with D=0, it remains in the display data RAM. Therefore, you can make it appear by changing D=0 into D=1.

SET ADDRESS (Y ADDRESS)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

Y address (AC0-AC5) of the display data RAM is set in the Y address counter. An address is set by instruction and increased by 1 automatically by read or write operations of display data.

SET PAGE (X ADDRESS)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	1	AC2	AC1	AC0

X address (AC0-AC2) of the display data RAM is set in the X address register. Writing or reading to or from MPU is executed in this specified page until the next page is set.

DISPLAY START LINE (Z ADDRESS)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	AC5	AC4	AC3	AC2	AC1	AC0

Z address (AC0-AC5) of the display data RAM is set in the display start line register and displayed at the top of the screen. When the display duty cycle is 1/64 or others (1/32-1/64), the data of total line number of LCD screen, from the line specified by display start line instruction, is displayed.

STATUS READ

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	BUSY	0	ON/OFF	RESET	0	0	0	0

• BUSY

When BUSY is 1, the Chip is executing internal operation and no instructions are accepted.

When BUSY is 0, the Chip is ready to accept any instructions.

• ON/OFF

When ON/OFF is 1, the display is OFF.

When ON/OFF is 0, the display is ON.

RESET

When RESET is 1, the system is being initialized.

In this condition, no instructions except status read can be accepted.

When RESET is 0, initializing has finished and the system is in usual operation condition.

WRITE DISPLAY DATA

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	D7	D6	D5	D4	D3	D2	D1	D0

Writes data (D0-D7) into the display data RAM. After writing instruction, Y address is increased by 1automatically.

READ DISPLAY DATA

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1	D7	D6	D5	D4	D3	D2	D1	D0

Reads data (D0-D7) from the display data RAM. After reading instruction, Y address is increased by 1 automatically.

12.Reliability

Content of Reliability Test (wide temperature, -20°C~70°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 15mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

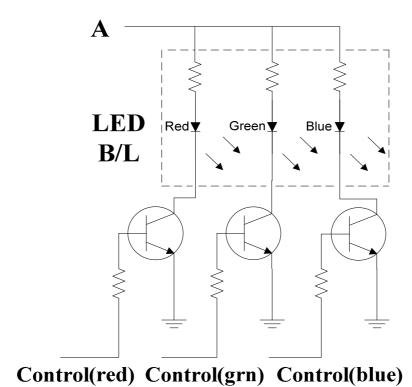
13.Backlight Information

PARAMETER	SYM	BOL	MIN	TYP	MAX	UNIT	TEST CONDITION	
		R	36	45	67.5			
Supply Current	ILED	G	36	45	67.5	mA	V=5.0V	
		В	36	45	67.5			
		R	1.8	1.9	2.0			
Supply Voltage	V	G	3.1	3.2	3.3	v	_	
		В	2.9	3.0	3.1			
Reverse Voltage	V	R	_	7.0	_	V	_	
T	IV	R	38	47.5			ILED(red)=45mA	
Luminous Intensity		IV	G	120.16	150.2	_	CD/M ²	ILED(green)=45mA
Intensity		В	13.6	17.0			ILED(blue)=45mA	
		R	620	625	630			
Wave Length	λ	G	515	520	525	nm	_	
		В	465	470	475			
	I	2	80K	100K			ILED≦15mA	
Life Time	(3	40K	50K		Hr.	For each LED Lamp	
	I	3	40K	50K			roi cacii LED Lamp	
Color				Rec	d, Green,	, Blue		

Note:

- 1. The LED B/L of "triple color" is designed for voltage driving, user have to follow The drive voltage that can make driving current in safety range (current between minimum and maximum).
- 2. owing to having 3 chips in one LED lamp, which caused many combinations of different wave length. This situation will caused wave length shifting while driving 2 colors or more in the same time.
- 3. The luminous intensity is measured on B/L surface only.

Backlight Drive Method



The driving circuit of suggestion is showed as above, owing to B/L being designed In parallel mode, so user can use transistor • FET or TRIC to control.

14. Inspection specification

NO	Item	Criterion	ſ	AQL		
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 				
02	Black or white spots on LCD (display only)	2.1 White and black spots on display three white or black spots present.2.2 Densely spaced: No more than two		2.5		
03	LCD black spots, white spots, contamination (non-display)	→X	IZEAcceptable Q TY $\Phi \le 0.10$ Accept no dense $\Phi \le 0.20$ 2 $\Phi \le 0.25$ 1 Φ 0 3) 1th Acceptable Q TY 3.002 Accept no dense	2.5		
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. Size $0.20 < \Phi$ $0.50 < \Phi$ $1.00 < \Phi$ Total 0	≤ 0.20 Accept no dense ≤ 0.50 3 ≤ 1.00 2	2.5		

NO	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD blace	ck spots, white spots, cont	amination	
		Symbols Define: x: Chip length y k: Seal width t: L: Electrode pad length 6.1 General glass chip 6.1.1 Chip on panel sur	ck spots, white spots, cont : Chip width z: Chip : Glass thickness a: LCE n: : face and crack between p	o thickness O side length anels:	AQL
	Chipped	z: Chip thickness $Z \le 1/2t$	y: Chip width Not over viewing area	x: Chip length $x \le 1/8a$	2.5
06	glass	$\frac{Z = 1/2t}{1/2t < z \le 2t}$	Not exceed 1/3k	$x \le 1/8a$	2.5
		⊙ If there are 2 or more 6.1.2 Corner crack:	chips, x is total length of e	ach chip.	
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x ≤ 1/8a	
		$1/2t < z \leq 2t$	Not exceed 1/3k	x ≦ 1/8a	
		⊙If there are 2 or more	chips, x is the total length	of each chip.	

NO	Item	Criterion	AQL
		Symbols:	
		x: Chip length y: Chip width z: Chip thickness	
		k: Seal width t: Glass thickness a: LCD side length	
		L: Electrode pad length	
		6.2 Protrusion over terminal :	
		6.2.1 Chip on electrode pad:	
		. 7	
		2	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5 \text{mm}$ $x \le 1/8 \text{a}$ $0 < z \le t$	
		6.2.2 Non-conductive portion:	
		•	
0.5	Glass		2.5
06	crack		2.5
		13	
		y Z	
		X	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$	
		⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must	
		remain and be inspected according to electrode terminal specifications.	
		⊙If the product will be heat sealed by the customer, the alignment mark	
		not be damaged.	
		6.2.3 Substrate protuberance and internal crack.	
		y: width x: length	
		$y \le 1/3L$ $x \le a$	
		у	
		•	

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	2.5 2.5 0.65 2.5 0.65 2.5 2.5 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
NO 12	Item	Criterion 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin	
	General appearance	must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet.	2.5 2.5 0.65 0.65 0.65

15. Material List of Components for RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

•		

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited	100	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm

Above limited value is set up according to RoHS.

- 2.Process for RoHS requirement:
- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250° C, 30 seconds Max.;

Connector soldering wave or hand soldering : 320° C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. $: 235\pm5^{\circ}\mathbb{C}$;

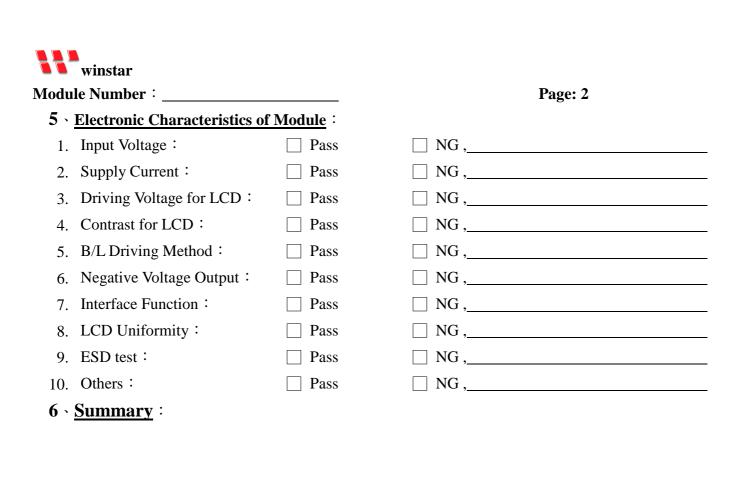
Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

16. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

		<u>le Estimat</u>	te Feedback Sheet	D 1					
	e Number:			Page: 1					
	Panel Specification:	□ Dogg							
	Panel Type:	☐ Pass							
2.	View Direction:	☐ Pass							
3.	Numbers of Dots: View Area:	☐ Pass							
4.	Active Area:	☐ Pass							
5.		☐ Pass							
6. 7.	Operating Temperature : Storage Temperature :	☐ Pass							
8.	Others:	1 ass							
	Mechanical Specification:								
2 <u>1.</u> 1.	PCB Size :	Pass	□ NG.						
2.	Frame Size:	Pass							
3.	Materal of Frame:	Pass							
4.	Connector Position:	Pass							
5.	Fix Hole Position:	☐ Pass							
6.	Backlight Position:	☐ Pass							
7.	Thickness of PCB:	☐ Pass							
8.	Height of Frame to PCB:	Pass							
9.	Height of Module:	Pass	☐ NG ,						
10	. Others:	Pass							
3 · <u>R</u>	Relative Hole Size :								
1.	Pitch of Connector:	☐ Pass	□ NG ,						
2.	Hole size of Connector:	☐ Pass	□ NG ,						
3.	Mounting Hole size:	☐ Pass	□ NG ,						
4.	Mounting Hole Type:	Pass	□ NG ,						
5.	Others:	Pass	☐ NG ,						
4 \ <u>B</u>	4 · Backlight Specification :								
1.	B/L Type:	Pass	☐ NG ,						
2.	B/L Color:	Pass	☐ NG ,						
3.	B/L Driving Voltage (Refere	nce for LED	Type): Pass	□ NG ,					
4.	B/L Driving Current:	Pass	☐ NG ,						
5.	Brightness of B/L:	Pass	☐ NG ,						
6.	B/L Solder Method:	Pass	☐ NG ,						
7.	Others:	Pass	☐ NG ,						

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Date: / /

Sales signature : ______